

## IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Patent Application of

Chi Wah CHENG et al

Date: January 8, 2002

Serial No.:

Group Art Unit:

Filed:

Examiner:

For: APPARATUS AND METHOD OF PLACING SOLDER BALLS ONTO A SUBSTRATE

U.S. Patent and Trademark Office  
 P.O. Box 2327  
 Arlington, VA 22202

## AMENDMENT/SUBMISSION

Prior to examination, please amend the application as follows.

## FEE CALCULATION

Any additional fee required has been calculated as follows:

If checked, "Small Entity" status is claimed.

NO. CLAIMS AFTER AMENDMENT	HIGHEST NO. PREVIOUSLY PAID FOR	EXTRA PRESENT	RATE	ADDIT. FEE
<u>TOTAL</u> 24	MINUS 20	* = 4	X (\$9 SE or \$18)	\$ 72.00
<u>INDEP.</u> 2	MINUS 3	** = 0	X (\$42 SE or \$84)	\$
FIRST PRESENTATION OF MULTIPLE DEPENDENT CLAIM			X (\$140 SE or \$280)	\$
<u>* not less than 20</u>			<u>TOTAL \$ 72.00</u>	

If any additional payment is required, a check which includes the calculated fee of \$72.00 (OFGS Check No. 8026) is attached.

In the event the actual fee is greater than the payment submitted or is inadvertently not enclosed or if any additional fee during the prosecution of this application is not paid, the Patent Office is authorized to charge the underpayment to Deposit Account No. 15-0700.